

PROD

V_{DS} (V) R_{DS(on)} (C

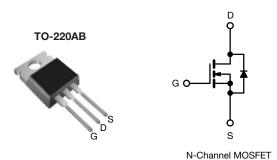
Q_q max.

Q_{gs} (nC)

Q_{gd} (nC)

Configuration

Power MOSFET



UCT SUMMARY					
	500)			
(2)	V _{GS} = 10 V	3.0			
(nC)	24				
	2.2				

13

Single

FEATURES

- Dynamic dV/dt rating
- Repetitive avalanche rated
- Fast switching
- · Ease of paralleling
- · Simple drive requirements
- Material categorization: for definitions of compliance please see <u>www.vishav.com/doc?99912</u>

Note

* This datasheet provides information about parts that are RoHS-compliant and / or parts that are non RoHS-compliant. For example, parts with lead (Pb) terminations are not RoHS-compliant. Please see the information / tables in this datasheet for details

DESCRIPTION

Third generation power MOSFETs from Vishay provide the designer with the best combination of fast switching, ruggedized device design, low on-resistance and cost-effectiveness.

The TO-220AB package is universally preferred for commercial-industrial applications at power dissipation levels to approximately 50 W. The low thermal resistance and low package cost of the TO-220AB contribute to its wide acceptance throughout the industry.

ORDERING INFORMATION	
Package	TO-220AB
Lead (Pb)-free	IRF820PbF
Lead (Pb)-free and halogen-free	IRF820PbF-BE3

ABSOLUTE MAXIMUM RATINGS (T _C	= 25 °C, unl	ess otherwis	se noted)			
PARAMETER			SYMBOL	LIMIT	UNIT	
Drain-source voltage			V _{DS}	500	V	
Gate-source voltage V _{GS} ± 20		v				
Continuous dusin suggest		$T_C = 25 ^{\circ}C$ $T_C = 100 ^{\circ}C$		2.5		
Continuous drain current	V _{GS} at 10 V	T _C = 100 °C	I _D	1.6	Α	
Pulsed drain current ^a			I _{DM}	8.0		
Linear derating factor				0.40	W/°C	
Single pulse avalanche energy ^b			E _{AS}	210	mJ	
Repetitive avalanche current a			I _{AR}	2.5	А	
Repetitive avalanche energy ^a			E _{AR}	5.0	mJ	
Maximum power dissipation $T_C = 25 ^{\circ}C$			P_{D}	50	W	
Peak diode recovery dV/dt c			dV/dt	3.5	V/ns	
Operating junction and storage temperature range			T _J , T _{stg}	-55 to +150	°C	
Soldering recommendations (peak temperature) d	ring recommendations (peak temperature) ^d For 10 s			300		
Mounting torque	6-32 or M3 screw			10	lbf ⋅ in	
Mounting torque	0-32 Of 1	vio sciew		1.1	N·m	

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11)
- b. V_{DD} = 50 V, starting T_J = 25 °C, L = 60 mH, R_q = 25 Ω , I_{AS} = 2.5 A (see fig. 12)
- c. $I_{SD} \le 2.5$ A, $dI/dt \le 50$ A/ μ s, $V_{DD} \le V_{DS}$, $T_{J} \le 150$ °C
- d. 1.6 mm from case



Vishay Siliconix

THERMAL RESISTANCE RAT	INGS			
PARAMETER	SYMBOL	TYP.	MAX.	UNIT
Maximum junction-to-ambient	R _{thJA}	-	62	
Case-to-sink, flat, greased surface	R _{thCS}	0.50	-	°C/W
Maximum junction-to-case (drain)	R _{thJC}	-	2.5	

PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static				L	L		
Drain-source breakdown voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$		500	-	-	V
V _{DS} temperature coefficient	$\Delta V_{DS}/T_{J}$	Reference	e to 25 °C, I _D = 1 mA	-	0.59	-	V/°C
Gate-source threshold voltage	V _{GS(th)}	V _{DS} =	· V _{GS} , I _D = 250 μA	2.0	-	4.0	V
Gate-source leakage	I _{GSS}		V _{GS} = ± 20 V	-	_	± 100	nA
	I _{DSS}	V _{DS} = 500 V, V _{GS} = 0 V		-	-	25	
Zero gate voltage drain current		V _{DS} = 400 V	', V _{GS} = 0 V, T _J = 125 °C	-	-	250	μA
Drain-source on-state resistance	R _{DS(on)}	V _{GS} = 10 V	I _D = 1.5 A ^b	-	-	3.0	Ω
Forward transconductance	9 _{fs}	V _{DS}	= 50 V, I _D = 1.5 A	1.5	-	-	S
Dynamic						•	
Input capacitance	C _{iss}	$V_{GS} = 0 V$		-	360	-	
Output capacitance	C _{oss}	1	$V_{DS} = 25 \text{ V},$	-	92	-	pF
Reverse transfer capacitance	C _{rss}	f = 1.0 MHz, see fig. 5		-	37	-	1
Total gate charge	Qg			-	-	24	
Gate-source charge	Q _{gs}	V _{GS} = 10 V	$I_D = 2.1 \text{ A}, V_{DS} = 400 \text{ V},$ see fig. 6 and 13 b	-	-	3.3	nC
Gate-drain charge	Q _{gd}		occ lig. o and ro	=	-	13	
Turn-on delay time	t _{d(on)}			-	8.0	-	
Rise time	t _r	V_{DD} = 250 V, I_D = 2.1 A, R_g = 18 Ω, R_D = 100 Ω, see fig. 10 b		-	8.6	-	ns
Turn-off delay time	t _{d(off)}			=	33	-	
Fall time	t _f			-	16	-	
Gate input resistance	Rg	f = 1 MHz, open drain		1.8	-	12.6	Ω
Internal drain inductance	L_D	Between lead, 6 mm (0.25") from package and center of die contact		-	4.5	-	- nH
Internal source inductance	L _S			-	7.5	-	
Drain-Source Body Diode Characteristic	cs						
Continuous source-drain diode current	I _S	MOSFET symbol showing the integral reverse p - n junction diode		-	-	2.5	_
Pulsed diode forward current ^a	I _{SM}			-	-	8.0	A
Body diode voltage	V _{SD}	T _J = 25 °C, I _S = 2.5 A, V _{GS} = 0 V ^b		-	-	1.6	V
Body diode reverse recovery time	t _{rr}	T _ 05 °C !	= 0.1 A dl/dt 100 A/c-	-	260	520	ns
Body diode reverse recovery charge	Q _{rr}	$T_J = 25 ^{\circ}\text{C}, I_F = 2.1 \text{A}, dI/dt = 100 \text{A/}\mu\text{s}$		-	0.7	1.4	nC
Forward turn-on time	t _{on}	Intrinsic to	n-on is dominated by L_S and L_D)			1-2)	

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11)
- b. Pulse width $\leq 300 \ \mu s$; duty cycle $\leq 2 \ \%$



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

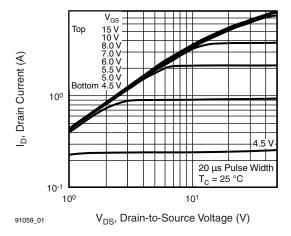


Fig. 1 - Typical Output Characteristics, $T_C = 25$ °C

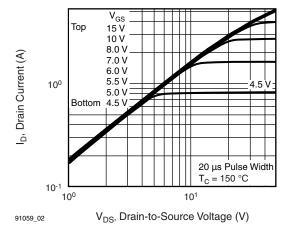


Fig. 2 - Typical Output Characteristics, $T_C = 150$ °C

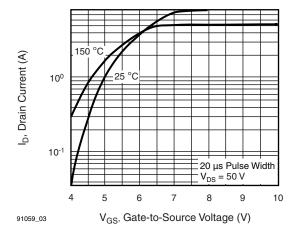


Fig. 3 - Typical Transfer Characteristics

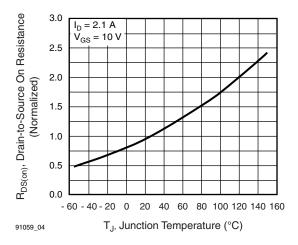


Fig. 4 - Normalized On-Resistance vs. Temperature

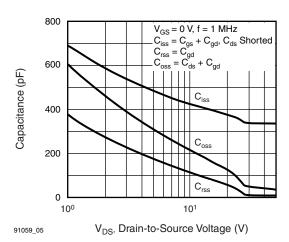


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

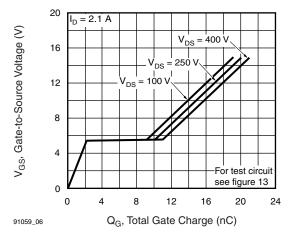


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage



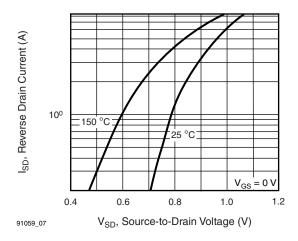


Fig. 7 - Typical Source-Drain Diode Forward Voltage

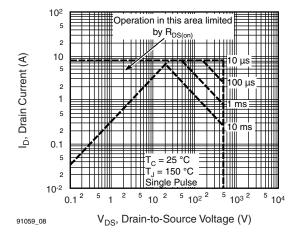


Fig. 8 - Maximum Safe Operating Area

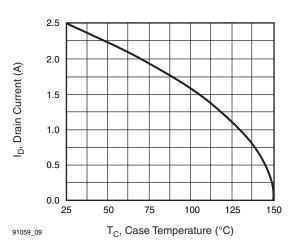


Fig. 9 - Maximum Drain Current vs. Case Temperature

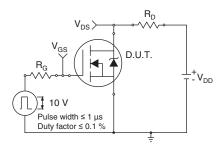


Fig. 10a - Switching Time Test Circuit

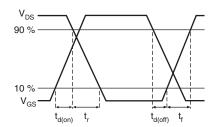


Fig. 10b - Switching Time Waveforms

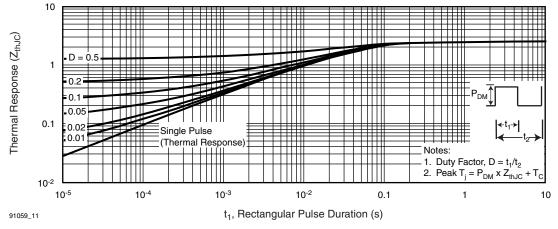


Fig. 11 - Maximum Effective Transient Thermal Impedance, Junction-to-Case



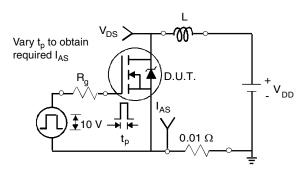


Fig. 12a - Unclamped Inductive Test Circuit

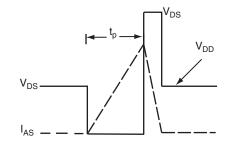


Fig. 12b - Unclamped Inductive Waveforms

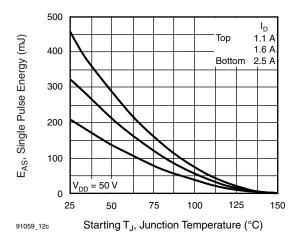


Fig. 12c - Maximum Avalanche Energy vs. Drain Current

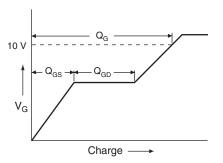


Fig. 13a - Basic Gate Charge Waveform

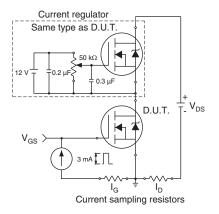
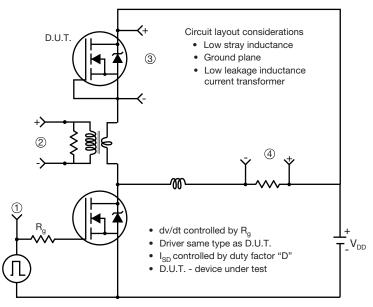


Fig. 13b - Gate Charge Test



Peak Diode Recovery dv/dt Test Circuit



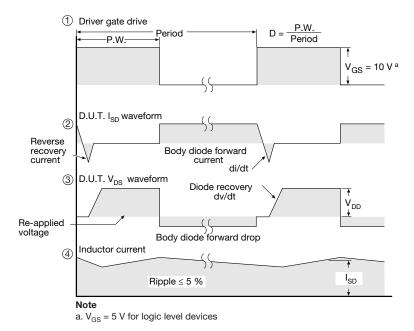
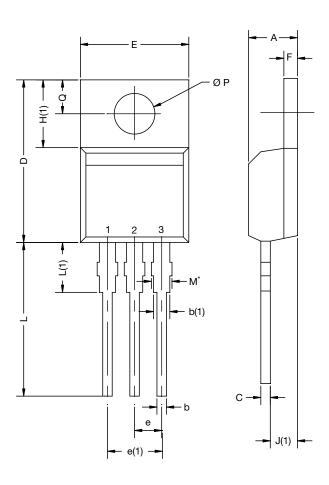


Fig. 14 - For N-Channel

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TO-220-1



DIM.	MILLIM	METERS	INC	HES
	MIN.	MAX.	MIN.	MAX.
Α	4.24	4.65	0.167	0.183
b	0.69	1.02	0.027	0.040
b(1)	1.14	1.78	0.045	0.070
С	0.36	0.61	0.014	0.024
D	14.33	15.85	0.564	0.624
Е	9.96	10.52	0.392	0.414
е	2.41	2.67	0.095	0.105
e(1)	4.88	5.28	0.192	0.208
F	1.14	1.40	0.045	0.055
H(1)	6.10	6.71	0.240	0.264
J(1)	2.41	2.92	0.095	0.115
L	13.36	14.40	0.526	0.567
L(1)	3.33	4.04	0.131	0.159
ØP	3.53	3.94	0.139	0.155
Q	2.54	3.00	0.100	0.118

Note

DWG: 6031

• $M^* = 0.052$ inches to 0.064 inches (dimension including protrusion), heatsink hole for HVM



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